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Titolo	Components, packaging and manufacturing technology II : selected, peer reviewed papers from the 2013 3rd International Conference on Packaging and Manufacturing Technology (ICCPMT 2013), December 31, 2013 - January 2, 2014, Brisbane Australia // edited by Andy Wu
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Descrizione fisica	1 online resource (245 p.)
Collana	Applied Mechanics and Materials, , 1662-7482 ; ; Volume 509
Disciplina	621.381
Soggetti	Electronic apparatus and appliances Electronic packaging Microelectronic packaging Manufacturing processes Electronic books.
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references and indexes.
Nota di contenuto	Components, Packaging and Manufacturing Technology II; Preface and Organizing Committee; Table of Contents; Chapter 1: Materials Science and Materials Processing Technology; Precise Determination of Band Gap Naturally via Absorption/Reflectance/Transmission Spectra; Preparation and Rheological Characterization of Cross-Linked Dialdehyde Carboxymethyl Cellulose; The Curing Behavior of Organosilicone Materials for Large-Power LED Packaging; The Status and Development of ECAP; Chapter 2: Mechanics; Dynamic Torsional Response of a Pile Partially Embedded in Saturated Soil Research on Internal Flow Field Simulation of Hydropower Station Pressure Steel Pipe Based on FLUENTA Discrimination Method of Saturated Sand Liquefaction Possibility Based on Support Vector Machine; Dragon Boat Straight Road Racing Rowing Technique Mechanical Movement Analysis; Dragon Boat Technology on the Influence of Fluid Mechanics Research; Vortex Stability Analysis Based on Coupling the Rubbing with BTA Boring Bar; Development and

Application on Ultrahigh Speed Grinding Processing Technology;
Chapter 3: Modelling, Design and Manufacturing
Multi-Objective Optimization of Vehicle Air Suspension Based on
Simulink-Mfile Mixed Programming Impacts of Solder Voids on Power
Devices' Thermal Characteristics; Research on Five-Axis NC Machining
Simulation for Four-Blade Propeller Based on UG&VERICUT;
Investigation on Aerodynamic Configuration of Monitoring Long
Endurance UAV; Passenger Vehicle Clutch Reliability Optimization Based
on the Stress-Strength Interference Model; Modularization Technology
Development Prospects; Design and Manufacture of a Forehand Attack
Exercising Device for Teaching and Training of Table Tennis
Development and Manufacture on the New Yoga Exercising
Device Research on Compensation Correction of Leak Impact Factor of
Kent Index Method; Application of MATLAB in Mechanical Optimal
Design; Analysis of Performance of Automotive Exhaust Muffler Based
on ANSYS Finite Element; Theoretical Research on a New Type Tube-in-
Tube Evaporative Condenser; Study on 3D Modeling and Flow Field
Simulation of Urea-SCR Catalytic Converter; Numerical Simulation for
Perforation-Caused Leakage Diffusion of Buried Gas Pipeline
Numerical Study on Heat Exchange Characteristics of Runways with
Snow-Melting System Using Geothermal Sources Research of the
Assembly Model Based on Parts Attribute Semantic; Chapter 4:
Automation, Control, Information Technology and MEMS; Slant-Face
Fiber Side Coupling of Vertical Cavity Surface Emitting Laser; The
Relationships of Prior Information and Interval Partition on the
Forecasting Effect of Fuzzy Time Series Two-Factor Model; Research on
the Behavior of Intelligent Role in Computer Games Based on Behavior
Tree; Building the Audit Information System in Cloud Computing
Environment
Study of Map-Reduce over Hadoop Based Cloud Computing
Environment

Sommario/riassunto

Collection of selected, peer reviewed papers from the 2013 3rd
International Conference on Components, Packaging and
Manufacturing Technology (ICCPMT 2013), December 31, 2013 -
January 2, 2014, Brisbane Australia. The 42 papers are grouped as
follows: Chapter 1: Materials Science and Materials Processing
Technology; Chapter 2: Mechanics; Chapter 3: Modelling, Design and
Manufacturing; Chapter 4: Automation, Control, Information
Technology and MEMS
